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HOSTAFORM® S 9364 LPB

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Hostaform® acetal copolymer grade S 9364LPB is a highly impact modified grade for low permeation. Hostaform® S 9364LPB provides a significant improvement in impact strength and flexibility over standard impact modified grades.
Chemical abbreviation according to ISO 1043-1: POM-HI

Product information

Resin Identification	POM-I		ISO 1043
Part Marking Code	>POM-I<		ISO 11469

Rheological properties

Melt volume-flow rate	0.6	cm^3/10min	ISO 1133
Temperature	190	°C	
Load	2.16	kg	

Typical mechanical properties

Tensile modulus	1650	MPa	ISO 527-1/-2
Tensile stress at yield, 50mm/min	43	MPa	ISO 527-1/-2
Tensile strain at yield, 50mm/min	16	%	ISO 527-1/-2
Flexural modulus	1550	MPa	ISO 178
Charpy impact strength, 23°C	N	kJ/m^2	ISO 179/1eU
Charpy impact strength, -30°C	N	kJ/m^2	ISO 179/1eU
Charpy notched impact strength, 23°C	21	kJ/m^2	ISO 179/1eA
Charpy notched impact strength, -30°C	11	kJ/m^2	ISO 179/1eA
Poisson's ratio	0.42[C]		

[C]: Calculated

Thermal properties

Melting temperature, 10°C/min	165	°C	ISO 11357-1/-3
Temperature of deflection under load, 1.8 MPa	75	°C	ISO 75-1/-2
Coefficient of linear thermal expansion (CLTE), parallel	120	E-6/K	ISO 11359-1/-2
Coefficient of linear thermal expansion (CLTE), normal	110	E-6/K	ISO 11359-1/-2

Physical/Other properties

Water absorption, 2mm	0.8	%	Sim. to ISO 62
Density	1370	kg/m^3	ISO 1183

Injection

Drying Recommended	no	
Drying Temperature	100	°C
Drying Time, Dehumidified Dryer	3 - 4	h
Processing Moisture Content	≤0.2	%
Melt Temperature Optimum	195	°C
Min. melt temperature	180	°C
Max. melt temperature	210	°C
Screw tangential speed	≤0.3	m/s
Mold Temperature Optimum	65	°C
Min. mould temperature	60	°C

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Max. mould temperature	70	°C
Hold pressure range	60 - 120	MPa

Characteristics

Processing	Injection Moulding, Blow Moulding
Delivery form	Pellets
Additives	Release agent
Special characteristics	High impact or impact modified

Additional information

Processing Notes

Pre-Drying

Drying is not normally required. If material has come in contact with moisture through improper storage or handling or through regrind use, drying to prevent splay and odor problems.

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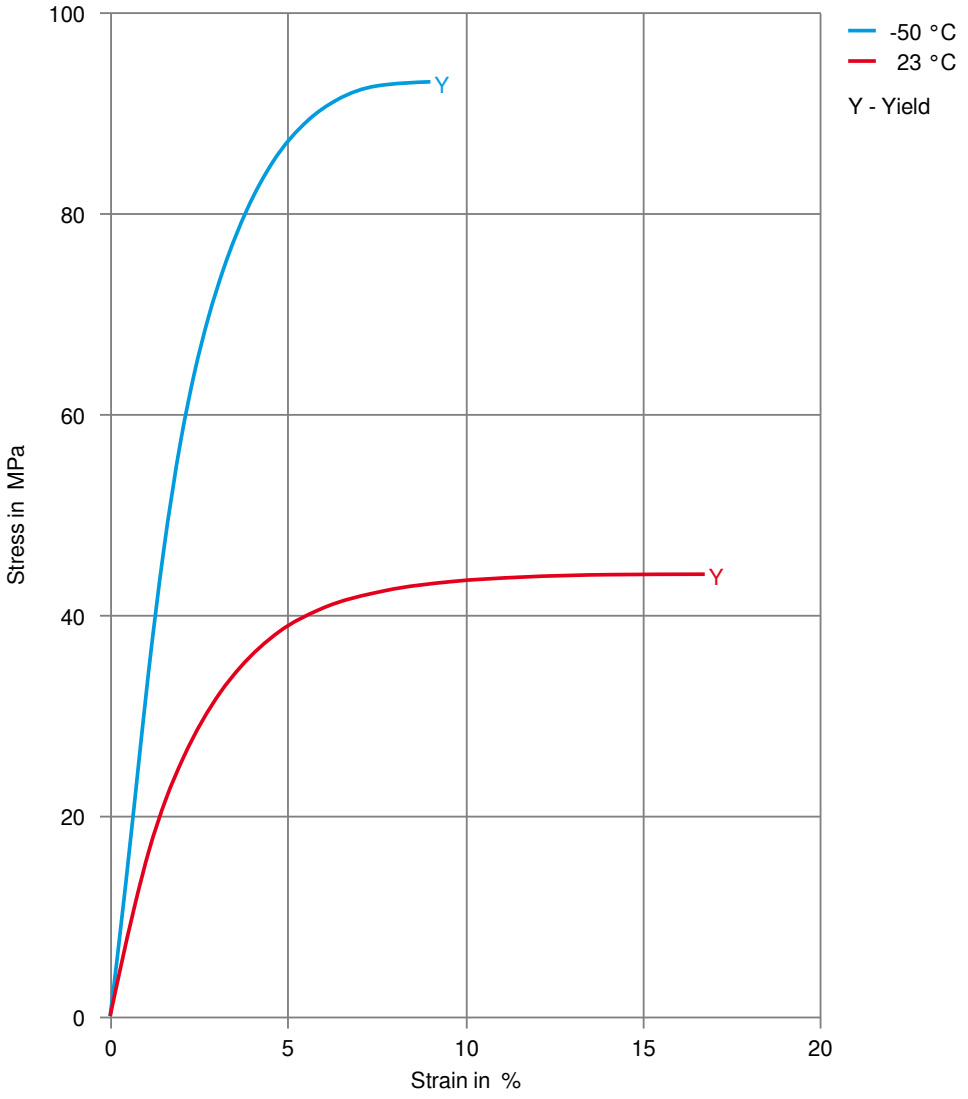
Stress-strain



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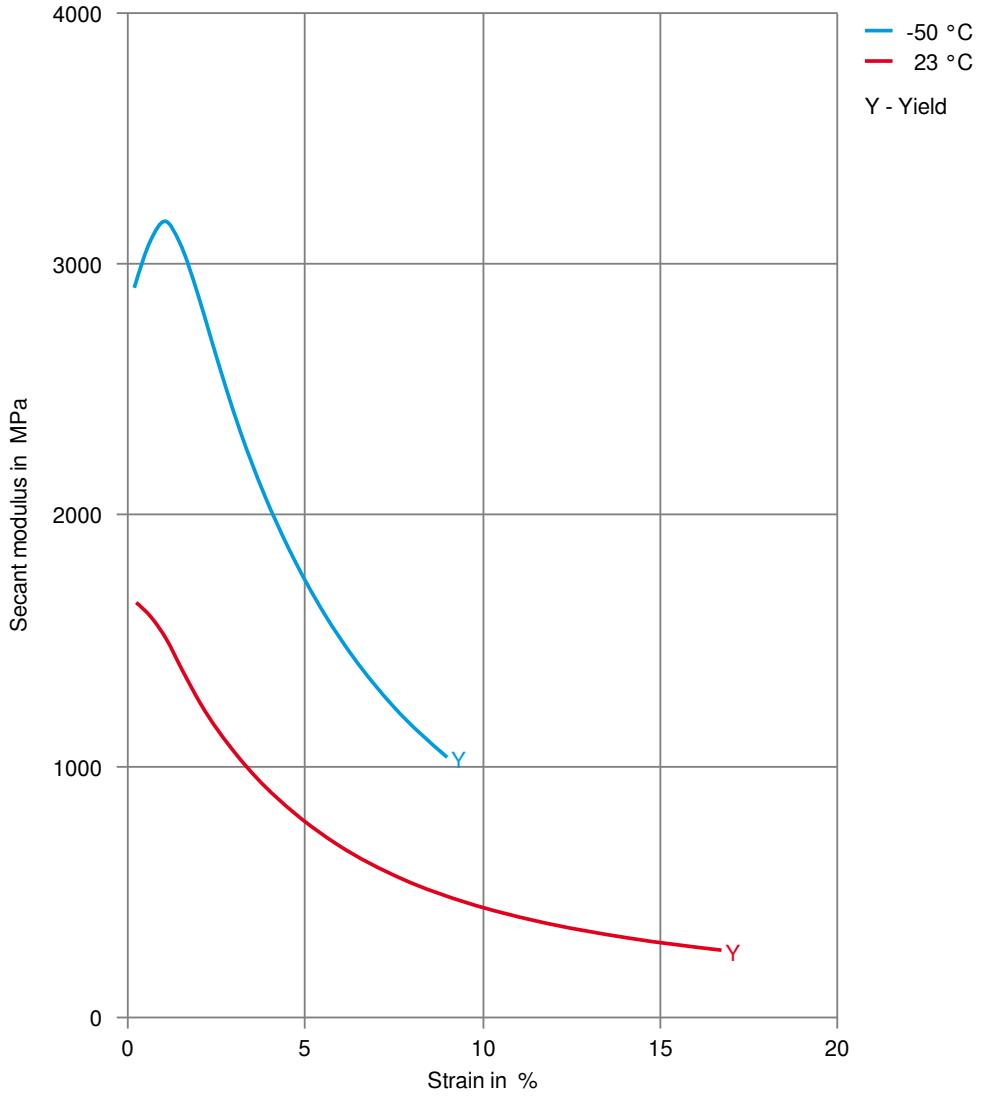
Secant modulus-strain



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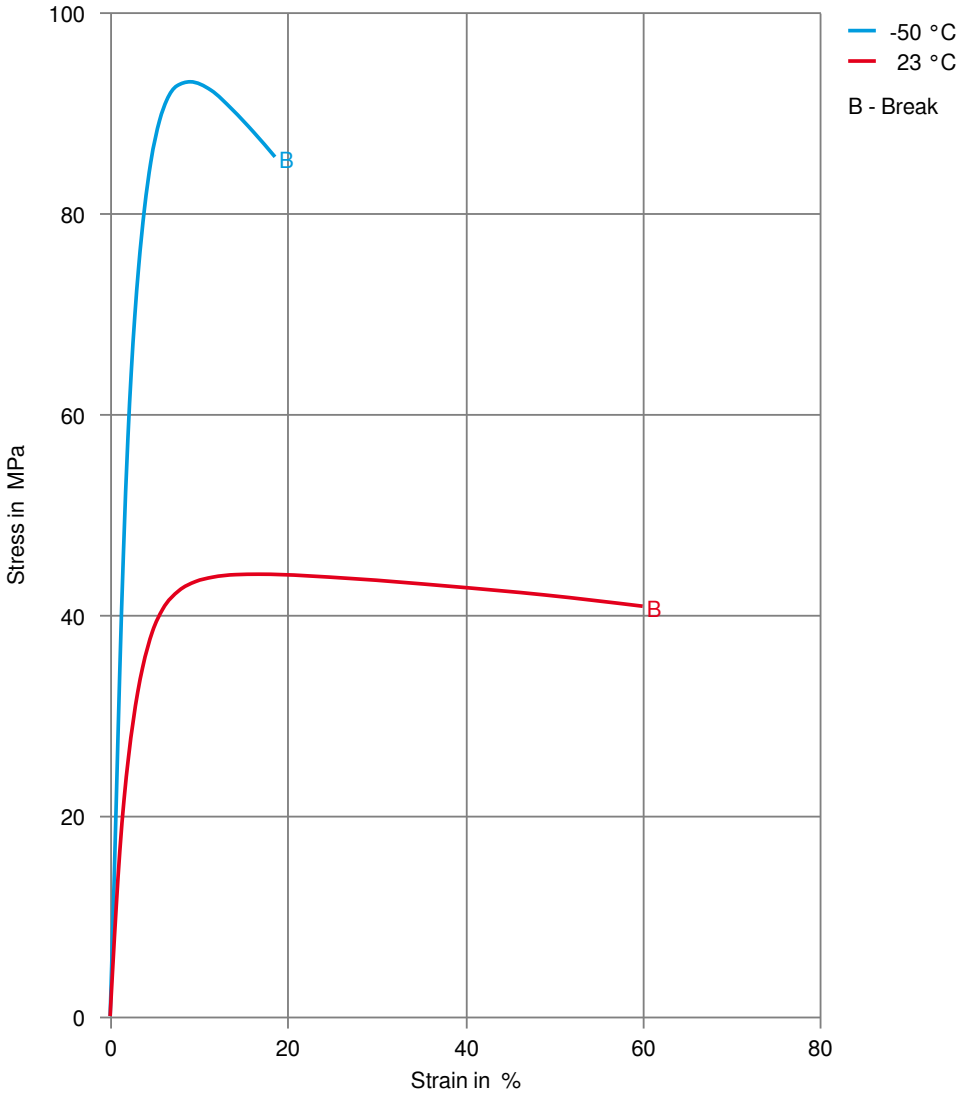
Stress-strain, 50mm/min



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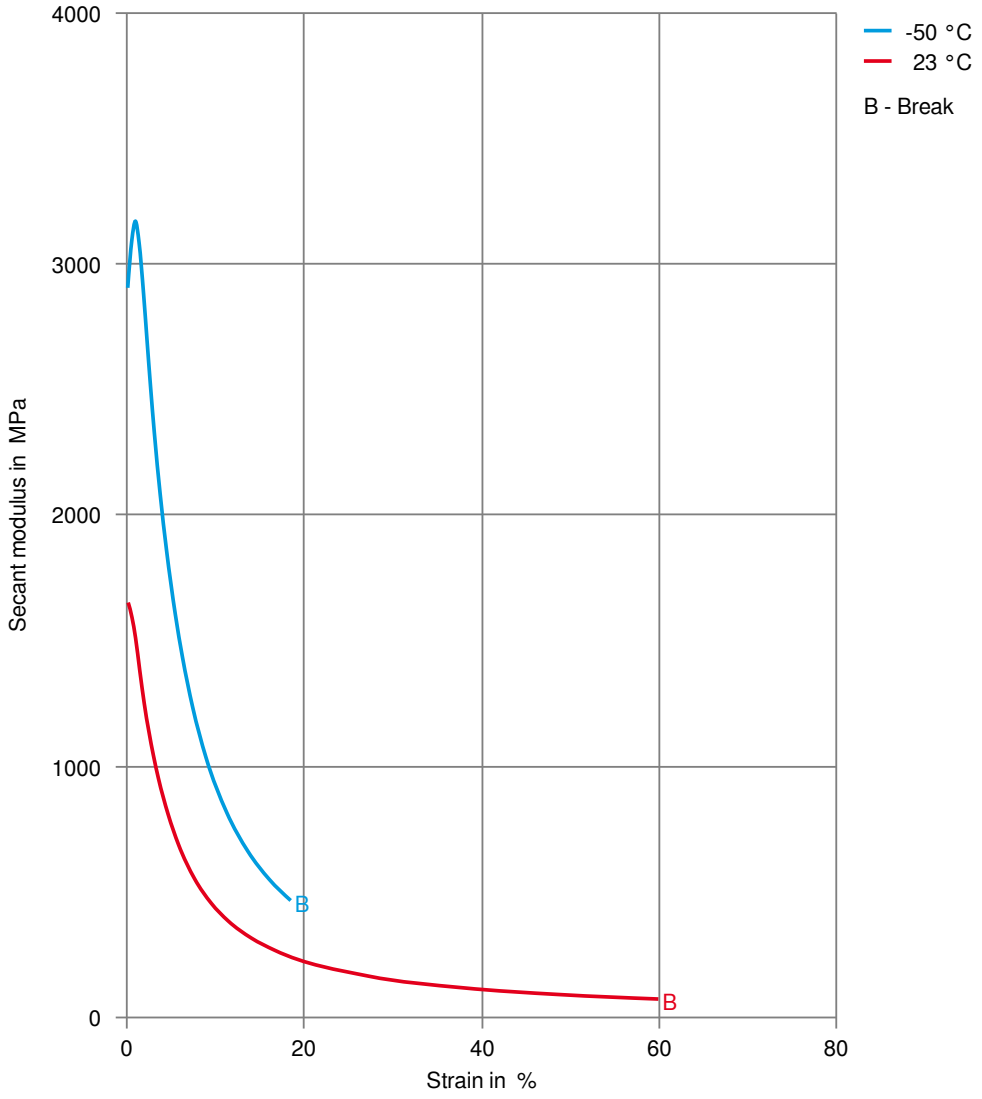
Secant modulus-strain, 50mm/min



Revised: 2024-12-03 Source: Celanese Materials Database